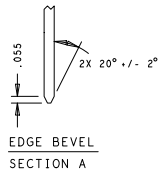


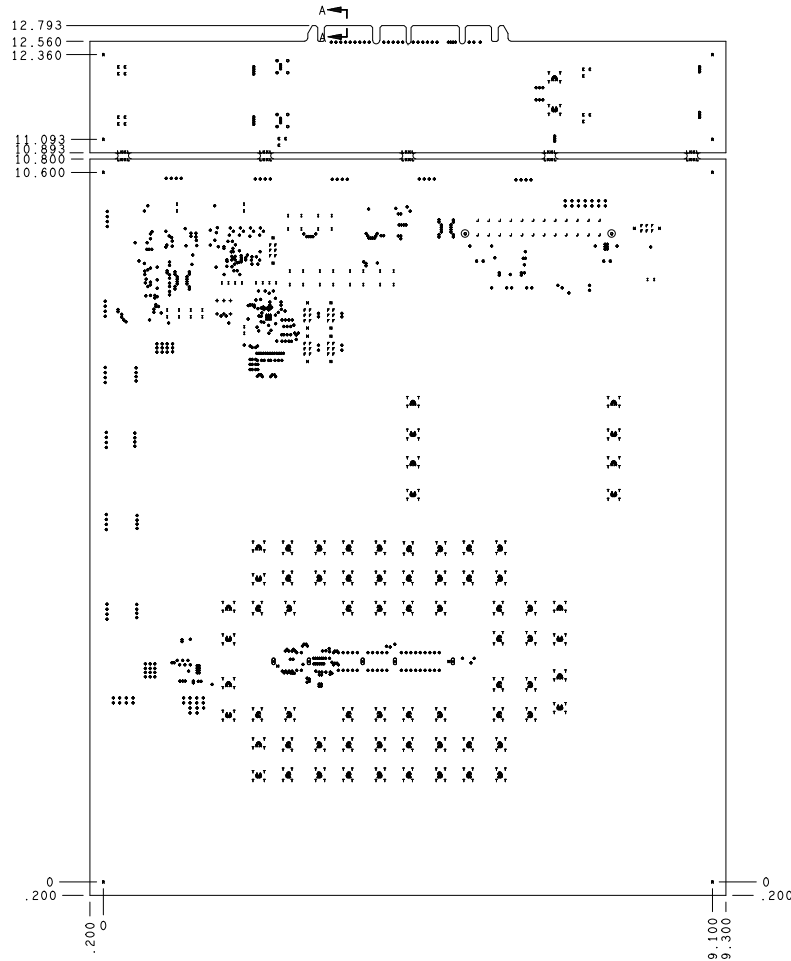
.0027	LAYER 1	TOP	1/2 OZ.
.021	LAYER 2	PLANE	1 OZ.
.0038	LAYER 3	SIGNAL	1 OZ.
.021	LAYER 4	SIGNAL	1 OZ.
.0027	LAYER 5	PLANE	1 OZ.
.0027	LAYER 6	BOTTOM	1/2 OZ.

.062 +/- .007
6 LAYERS



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED SIZE	TOLERANCE DRILL	PLATED	QTY
*	8.0	+3.0/-3.0	PLATED	738
*	8.02	+3.0/-7.0	PLATED	638
*	10.0	+3.0/-5.0	PLATED	9
*	10.0	+4.0/-10.0	PLATED	6
*	12.0	+3.0/-10.0	PLATED	17
*	28.0	+3.0/-3.0	PLATED	17
*	31.0	+2.0/-2.0	PLATED	36
*	32.0	+3.0/-3.0	PLATED	328
*	38.0	+3.0/-3.0	PLATED	4
*	42.9134	+9.8425/-9.8425	PLATED	6
*	47.0	+3.0/-3.0	PLATED	48
*	55.0	+3.0/-3.0	PLATED	24
*	28.0	+3.0/-3.0	NON-PLATED	20
*	42.0	+3.0/-3.0	NON-PLATED	20
*	43.3071	+2.0/-2.0	NON-PLATED	2
*	47.0	+2.0/-2.0	NON-PLATED	12
*	50.0	+1.0/-2.0	NON-PLATED	8
*	118.0	+3.0/-3.0	NON-PLATED	2
*	125.0	+2.0/-0.0	NON-PLATED	8
8	96.4567x43.3071	+3.0/-3.0	PLATED	5

TOTAL HOLES: 1948



NOTES:

1. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW THE REQUIREMENTS OF IPC-2221, 2222 AND IPC-6011, 6012, TYPE 3, CLASS 2.
2. MATERIAL: MEGTRON6 R-5775G OR EQUIVALENT IAW IPC-4101. MUST HAVE UL FLAMMABILITY RATING OF 94V-0 OR BETTER. BOARD MUST BE UL RECOGNIZED AND VENDOR SHALL AFFIX UL LISTING DESIGNATION ON PRINTED CIRCUIT BOARD. THIS BOARD IS INTENDED FOR LEAD-FREE ASSEMBLY.(ROHS COMPLIANT)
3. FINISH:IMMERSION GOLD (ENIG) 2-6 MICROINCHES OVER NICKEL 100 MICROINCHES MIN. FULL BODY IMMERSION GOLD ACCEPTED.
4. APPLY SOLDER MASK, IAW IPC-SM-840, CLASS H, TYPE B1 (LP1) COLOR GREEN, MATTE FINISH. ALL SOLDER PADS MUST BE 100% FREE OF SOLDER MASK.
5. APPLY SILKSCREEN TO BOTH SIDES IAW MARKING TEMPLATES. USING WHITE NON-CONDUCTIVE EPOXY INK. VENDOR MAY VIA CAP OR PLUG VIAS BEFORE FINAL SOLDER MASK TO AVOID TRIMMING OF SILKSCREEN. SILKSCREEN INK NOT ALLOWED ON ANY EXPOSED ETCH. VENDOR TO DETERMINE BEST PROCESS TO ENSURE THIS.
6. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. VENDOR MUST USE IPC D-356 NETLIST PROVIDED PRIOR TO BOARD FABRICATION AND COMPARE AGAINST GERBER DATA AND REPORT ANY DISCREPENCIES.
7. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING. TOLERANCE OF +/- .003. FINISH HOLE SIZES LESS THAN .012, TOLERANCE SHALL BE +.003 -.012
8. MARK DATE CODE AND MANUFACTURERS IDENTIFICATION ON SOLDER SIDE PER IPC-6011, 6012.
9. DIMENSIONING AND TOLERANCING IAW ANSI Y14.5.
10. ALL PATTERNS ARE VIEWED FROM THE COMPONENT SIDE LOOKING THROUGH THE BOARD.
11. VENDOR TO REMOVE ALL BURRS AND SHARP EDGES.
12. BOW AND TWIST NOT TO EXCEED 1 % OVER ENTIRE AREA.
13. ALL INSIDE RADII SHALL BE .062 UNLESS OTHERWISE SPECIFIED.
14. VENDOR IS ALLOWED TO FOLLOW BOARD OUTLINE FOR SIZE OF BOARD. VENDOR IS ALSO ALLOWED TO DO THE FOLLOWING: REMOVE INTERNAL NON FUNCTIONAL PADS; ADD TEAR DROPPING AND REMOVE SOLDER MASK SLIVERS LESS THAN .003 TO ENHANCE PRODUCIBILITY.
15. BOARD TO BE PANELIZE IN AN ARRAY WITH RAILS TOOLING HOLES AND FIDUCIALS. VENDOR TO SEND PROPOSED ARRAY FOR APPROVAL BEFORE PROCEEDING WITH BUILD.
16. CONTROLLED IMPEDANCE TRACES .004 WIDE ON LAYERS 1 AND 6 SHALL MEASURE 50 OHMS +/- 10%. VENDOR IS ALLOWED TO MAKE ADJUSTMENTS TO MEET CONTROLLED IMPEDANCE REQUESTED.
17. DIFFERENTIAL CONTROLLED IMPEDANCE TRACES ARE AS FOLLOWS:

LAYER	WIDTH	SPACE	REF LAYER	IMPEDANCE	TOLERANCE
1	.005	.007	2	85 OHM	+/- 20%
6	.005	.007	5	85 OHM	+/- 20%
18. ALL (.008) DIA HOLES USED IN MMPX CONNECTORS SHALL BE EPOXY FILLED, PLANERIZED AND PLATED OVER SURFACE TO BE SMOOTH AND FLAT TO ENSURE SOLDERABILITY.

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TO 1 OF 1			
DATE	REV	BY	CHK
08/10/2010	1	WJ	WJ